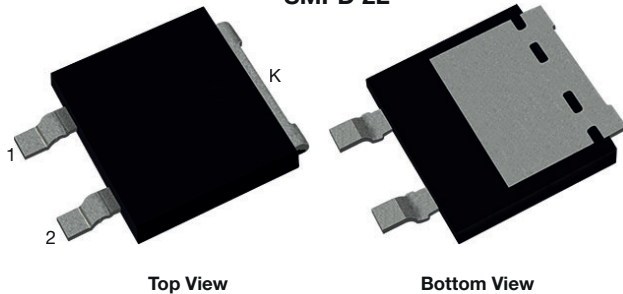


Surface-Mount ESD Capability Rectifiers

eSMP® Series SMPD 2L



LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	12 A
V_{RRM}	400 V, 600 V
I_{FSM}	125 A
V_F at $I_F = 12$ A ($T_J = 125$ °C)	0.96 V
I_R	20 μ A
T_J max.	175 °C
Package	SMPD 2L
Circuit configuration	Single

FEATURES

- Creepage and clearance distance 3.7 mm typical
- Very low profile - typical height of 1.7 mm
- Ideal for automated placement
- Oxide planar chip junction
- Low forward voltage drop
- ESD capability
- AEC-Q101 qualified available
- Meets MSL level 1, per J-STD-020, LF maximum peak 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

TYPICAL APPLICATIONS

General purpose, power line polarity protection, in both consumer and automotive on board charger (OBC) applications.

MECHANICAL DATA

Case: SMPD 2L

Molding compound meets UL 94 V-0 flammability rating
Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 2 whisker test, HM3 suffix meets JESD 201 class 2 whisker test

Polarity: as marked

MAXIMUM RATINGS ($T_J = 25$ °C unless otherwise noted)				
PARAMETER	SYMBOL	SE12DTG	SE12DTJ	UNIT
Device code		SE12DTG	SE12DTJ	
Maximum repetitive peak reverse voltage	V_{RRM}	400	600	V
Maximum DC forward current	$I_F^{(1)}$	12		A
	$I_F^{(2)}$	3.2		
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I_{FSM}	125		A
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +175		°C

Notes

(1) With heatsink

(2) Free air, mounted on recommended copper pad area



ELECTRICAL CHARACTERISTICS (T _A = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I _F = 6 A	T _J = 25 °C	V _F ⁽¹⁾	0.95	-	V
	I _F = 12 A			1.04	1.15	
	I _F = 6 A	T _J = 125 °C		0.85	-	
	I _F = 12 A			0.96	1.10	
Reverse current	Rated V _R	T _J = 25 °C	I _R ⁽²⁾	-	20	µA
		T _J = 125 °C		27	150	
Typical reverse recovery time	I _F = 0.5 A, I _R = 1.0 A, I _{rr} = 0.25 A		t _{rr}	3000	-	ns
Typical junction capacitance	4.0 V, 1 MHz		C _J	90	-	pF

Notes

- (1) Pulse test: 300 µs pulse width, 1 % duty cycle
- (2) Pulse test: Pulse width ≤ 40 ms

THERMAL CHARACTERISTICS (T _A = 25 °c unless otherwise noted)				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Thermal resistance	R _{θJA} ⁽¹⁾⁽²⁾	60	75	°C/W
	R _{θJC} ⁽³⁾	1.6	2	

Notes

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient: dP_D/dT_J < 1/R_{θJA}
- (2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint
- (3) Thermal resistance junction-to-mount to follow JEDEC® 51-14 transient dual interface test method (TDIM)

IMMUNITY TO ELECTRICAL STATIC DISCHARGE TO THE FOLLOWING STANDARDS (T _A = 25 °C unless otherwise noted)					
STANDARD	TEST TYPE	TEST CONDITIONS	SYMBOL	CLASS	VALUE
AEC-Q101-001	Human body model (contact mode)	C = 100 pF, R = 1.5 kΩ	V _C	H3B	> 8 kV

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
SE12DTJ-M3/I	0.52	I	2000 / reel	13" diameter plastic tape and reel
SE12DTJHM3/I ⁽¹⁾	0.52	I	2000 / reel	13" diameter plastic tape and reel

Note

- (1) AEC-Q101 qualified

RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

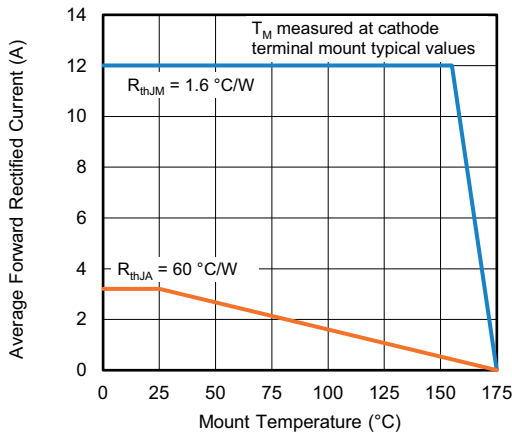


Fig. 1 - Forward Current Derating Curve

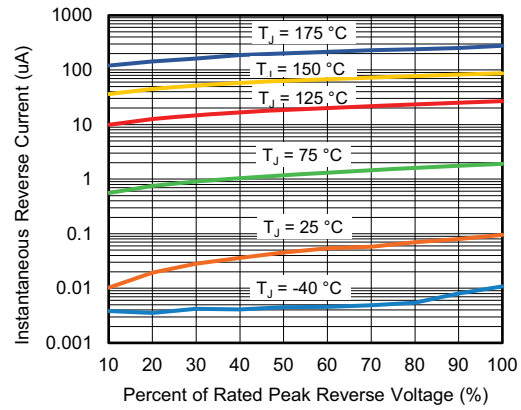


Fig. 4 - Typical Reverse Leakage Characteristics

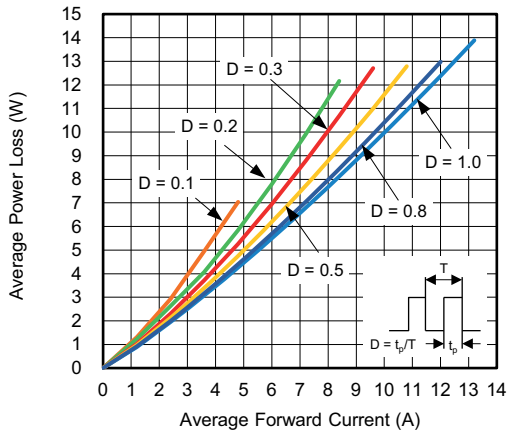


Fig. 2 - Forward Power Loss Characteristics

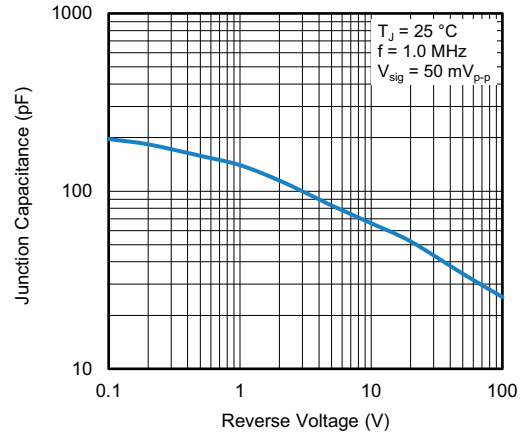


Fig. 5 - Typical Junction Capacitance

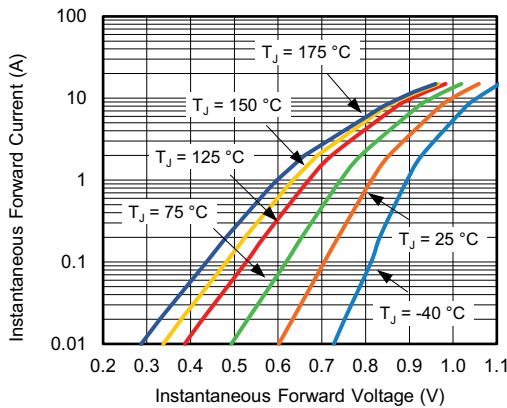


Fig. 3 - Typical Instantaneous Forward Characteristics

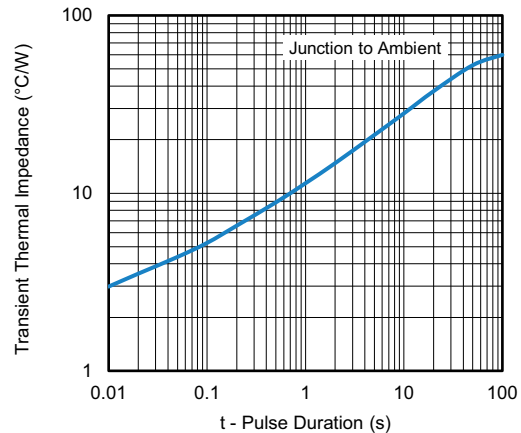
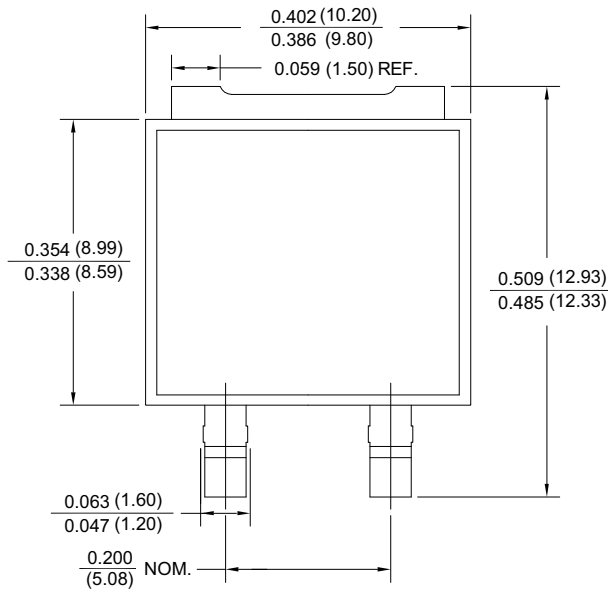


Fig. 6 - Typical Transient Thermal Impedance

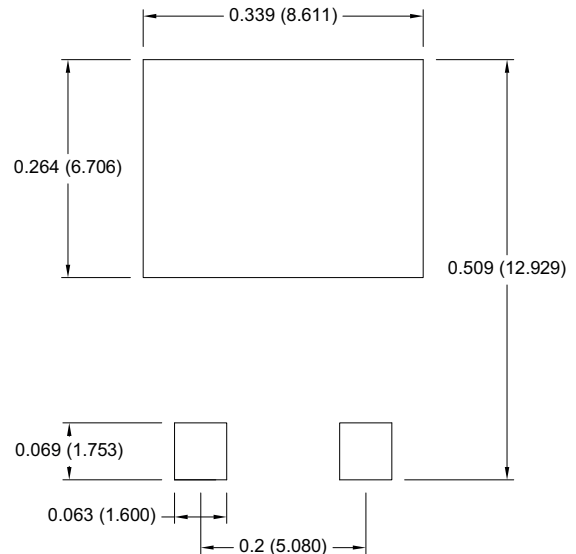
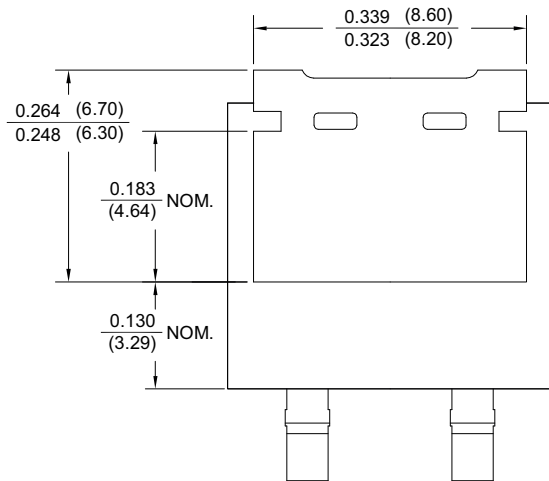


PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

SMPD 2L



Mounting Pad Layout



Note

- The suggested mounting pad layout is provided for reference only, as actual pad layouts may vary depending on application



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